

Octal Buffer/Driver With 3-State Outputs

1 FEATURES

- **Power-Supply Range: 1.65V to 5.5V**
- **V_{CC} Isolation: If V_{CC} is at GND, Both Ports are in the High-Impedance State**
- **I_{OFF}: Supports Partial-Power-Down Mode Operation**
- **Extended Temperature: -40°C to +125°C**

2 APPLICATIONS

- Handset
- Smartphone
- Tablet
- Desktop PC

3 DESCRIPTIONS

This RS244 is an octal non-inverting buffer/driver with 3-state outputs. The 3-state outputs are controlled by the output enable inputs $\overline{1OE}$ and $\overline{2OE}$. A HIGH on \overline{OE} causes the outputs to assume a high impedance OFF-state. V_{CC} supporting operating voltage from 1.65 V to 5.5 V.

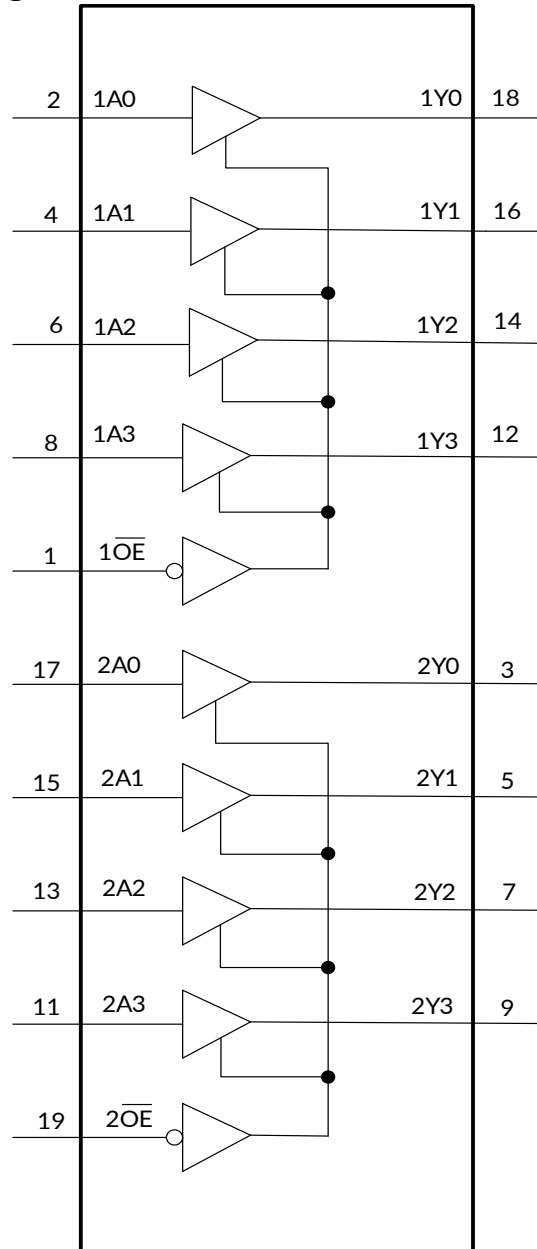
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor, the minimum value of the resistor is determined by the current-sinking capability of the driver.

Device Information ⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
RS244	TSSOP20	6.50mm×4.40mm
	SOP20	12.80mm×7.50mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 Functional Block Diagram



Function Table

INPUTS		OUTPUT
\overline{OE}	A PORT	Y PORT
L	H	H
L	L	L
H	X	Hi-Z

NOTE:
H=HIGH voltage level
L=LOW voltage level
X=don't care
Z=high impedance OFF-state

Table of Contents

1 FEATURES	1
2 APPLICATIONS	1
3 DESCRIPTIONS	1
4 Functional Block Diagram	2
5 Revision History	4
6 PACKAGE/ORDERING INFORMATION ⁽¹⁾	5
7 PIN CONFIGURATIONS	6
8 SPECIFICATIONS	7
8.1 Absolute Maximum Ratings	7
8.2 ESD Ratings	7
8.3 Recommended Operating Conditions	8
8.4 Electrical Characteristics	9
8.5 Switching Characteristics	10
8.6 Operating Characteristics	10
8.7 Typical Characteristics	11
9 Parameter Measurement Information	12
10 PACKAGE OUTLINE DIMENSIONS	13
11 TAPE AND REEL INFORMATION	15

5 Revision History

Note: Page numbers for previous revisions may differ from page numbers in the current version.

VERSION	Change Date	Change Item
A.1	2021/02/27	Initial version completed
A.2	2021/08/18	Delete Switching Characteristics redundant content in Page 9@A.1 Version.
A.3	2023/09/06	1. Update ESD Ratings on Page5@RevA.2 2. Add Package thermal impedance on Page5@RevA.2 3. Update PACKAGE OUTLINE DIMENSIONS
A.3.1	2024/02/26	Modify packaging naming

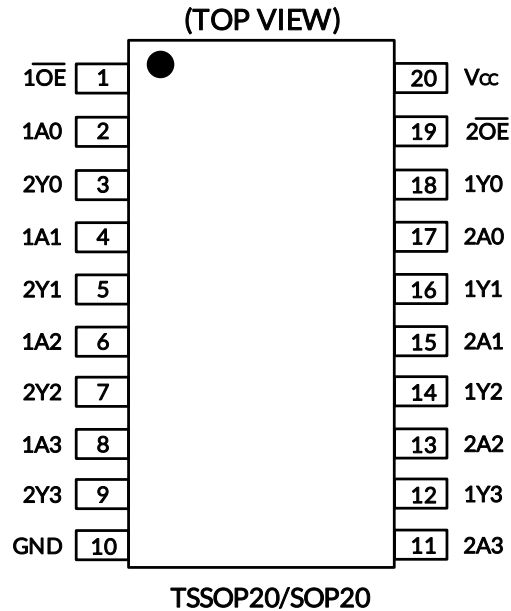
6 PACKAGE/ORDERING INFORMATION ⁽¹⁾

PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING ⁽²⁾	MSL ⁽³⁾	PACKAGE OPTION
RS244	RS244YTSS20	-40°C ~+125°C	TSSOP20	RS244	MSL3	Tape and Reel,4000
	RS244YS20	-40°C ~+125°C	SOP20	RS244	MSL3	Tape and Reel,1500

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information(data code and vendor code), the logo or the environmental category on the device.
- (3) MSL, The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications.

7 PIN CONFIGURATIONS



PIN DESCRIPTION

PIN	NAME	TYPE ⁽¹⁾	FUNCTION
TSSOP20/SOP20			
1	$\overline{1OE}$	I	Output Enable (Active Low). Pull $\overline{1OE}$ high to place all outputs in 3-state mode.
2	1A0	I	Input
3	2Y0	O	Output
4	1A1	I	Input
5	2Y1	O	Output
6	1A2	I	Input
7	2Y2	O	Output
8	1A3	I	Input
9	2Y3	O	Output
10	GND	G	Ground.
11	2A3	I	Input
12	1Y3	O	Output
13	2A2	I	Input
14	1Y2	O	Output
15	2A1	I	Input
16	1Y1	O	Output
17	2A0	I	Input
18	1Y0	O	Output
19	$\overline{2OE}$	I	Output Enable (Active Low). Pull $\overline{2OE}$ high to place all outputs in 3-state mode.
20	V _{cc}	P	Supply voltage. $1.65V \leq V_{cc} \leq 5.5V$

(1) I=input, O=output, I/O=input and output, P=power

8 SPECIFICATIONS

8.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

SYMBOL	PARAMETER		MIN	MAX	UNIT
V _{CC}	Supply Voltage Range		-0.5	6.5	V
V _I ⁽²⁾	Input Voltage Range	A port	-0.5	6.5	V
		Control inputs	-0.5	6.5	V
V _O ⁽²⁾	Voltage range applied to any output in the high-impedance or power-off state	Y port	-0.5	6.5	V
V _O ⁽²⁾⁽³⁾	Voltage range applied to any output in the high or low state	Y port	-0.5	V _{CC} +0.5	V
I _{IK}	Input clamp current	V _I <0		-50	mA
I _{OK}	Output clamp current	V _O <0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
θ _{JA}	Package thermal impedance ⁽⁴⁾	TSSOP20		40	°C/W
		SOP20		40	
T _J	Junction Temperature ⁽⁵⁾		-40	150	°C
T _{stg}	Storage temperature		-65	150	

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value of V_{CC} are provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD-51.

(5) The maximum power dissipation is a function of T_{J(MAX)}, R_{θJA}, and T_A. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} - T_A) / R_{θJA}. All numbers apply for packages soldered directly onto a PCB.

8.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), MIL-STD-883K METHOD 3015.9	±1500	V
		Charged-device model (CDM), ANSI/ESDA/JEDEC JS-002-2018	±1500	V
		Machine Model (MM), JESD22-A115	±200	V



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.3 Recommended Operating Conditions

V_{CC} is the supply voltage associated with the input port and output port. ⁽¹⁾⁽²⁾

PARAMETER		V _{CC}	MIN	TYP	MAX	UNIT
Supply voltage	V _{CC}		1.65		5.5	V
High-level input Voltage (V _{IH})	Inputs ⁽³⁾	1.65V to 1.95V	V _{CC} x0.65			V
		2.3V to 2.7V	1.7			
		3V to 3.6V	2			
		4.5V to 5.5V	V _{CC} x0.7			
Low-level input Voltage (V _{IL})	Inputs ⁽³⁾	1.65V to 1.95V			V _{CC} x0.35	V
		2.3V to 2.7V			0.7	
		3V to 3.6V			0.8	
		4.5V to 5.5V			V _{CC} x0.3	
Input voltage (V _I)	Input voltage		0		5.5	V
Output voltage (V _O)	Output voltage		0		V _{CC}	V
High-level output current (I _{OH})		1.65V to 1.95V			-4	mA
		2.3V to 2.7V			-8	
		3V to 3.6V			-24	
		4.5V to 5.5V			-32	
Low-level output current (I _{OL})		1.65V to 1.95V			4	mA
		2.3V to 2.7V			8	
		3V to 3.6V			24	
		4.5V to 5.5V			32	
Input transition rise or fall rate(Δt/Δv)	Data inputs	1.65V to 1.95V			20	ns/V
		2.3V to 2.7V			20	
		3V to 3.6V			10	
		4.5V to 5.5V			5	
T _A Operating free-air temperature			-40		125	°C

(1) All unused or driven (floating) data inputs (I/Os) of the device must be held at logic HIGH or LOW (preferably V_{CC} or GND) to ensure proper device operation and minimize power.

(2) All unused control inputs must be held at V_{CC} or GND to ensure proper device operation and minimize power consumption.

(3) For V_{CC} values not specified in the data sheet, V_{IH} min = V_{CC} × 0.7 V, V_{IL} max = V_{CC} × 0.3 V.

8.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	CONDITIONS	V _{CC}	TEMP	MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
V _{OH}	I _{OH} = -100 μA V _I = V _{IH}	1.65V to 4.5V	Full	V _{CC} -0.1			V
	I _{OH} = -4mA V _I = V _{IH}	1.65V		1.2			
	I _{OH} = -8mA V _I = V _{IH}	2.3V		1.9			
	I _{OH} = -24mA V _I = V _{IH}	3V		2.4			
	I _{OH} = -32mA V _I = V _{IH}	4.5V		3.8			
V _{OL}	I _{OL} = 100 μA V _I = V _{IL}	1.65V to 4.5V	Full			0.1	V
	I _{OL} = 4mA V _I = V _{IL}	1.65V				0.45	
	I _{OL} = 8mA V _I = V _{IL}	2.3V				0.3	
	I _{OL} = 24mA V _I = V _{IL}	3V				0.55	
	I _{OL} = 32mA V _I = V _{IL}	4.5V				0.55	
I _I	V _I = 5.5V or GND	5.5V	+25°C			±1	μA
I _{off}	V _I or V _O = 0 to 5.5V	0V	+25°C			±1	μA
			Full			±2	
I _{oz} ⁽³⁾	V _O = V _{CC} or GND, OE = V _{IH}	1.65V to 5.5V	+25°C			±1	μA
			Full			±2	
I _{CC}	V _{CC} supply current V _I = V _{CC} or GND ⁽⁴⁾ I _O = 0	1.65V to 5.5V	+25°C			1	μA
			Full			5	
		0V	Full			-2	
ΔI _{CC}	One A port at V _{CC} - 0.6V, Y port = open	3V to 5.5V	Full			50	μA
C _I	V _I = V _{CC} or GND	3.3V	+25°C		8.5		pF
C _O	V _O = V _{CC} or GND	3.3V	+25°C		8.5		pF

(1) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

(3) For I/O ports, the parameter I_{oz} includes the input leakage current.

(4) Hold all unused data inputs of the device at V_{CC} or GND to assure proper device operation.

8.5 Switching Characteristics

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =1.8V ±0.15V		V _{CC} =2.5V ±0.2V		V _{CC} =3.3V ±0.3V		V _{CC} =5V ±0.5V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	An	Yn	1.7	21.6	1.3	9.1	1.0	7.4	0.8	7.1	ns
t _{PHL}											
t _{PHZ}	\overline{OE}	Yn	2.4	32.2	1.9	12.9	1.7	12.0	1.3	10.2	ns
t _{PLZ}											
t _{PZH}	\overline{OE}	Yn	1.8	31.9	1.5	16	1.2	12.6	0.9	10.8	ns
t _{PZL}											

8.6 Operating Characteristics

T_A=25°C

PARAMETER		TEST CONDITIONS	V _{CC} =1.8V	V _{CC} =2.5V	V _{CC} =3.3V	V _{CC} =5V	UNIT
			TYP	TYP	TYP	TYP	
C _{pd} ⁽¹⁾	Outputs enabled	C _L =0, f=10MHz, t _r =t _f =1ns	42	42	43	44	pF
	Outputs disabled		2	2	2	3	

(1) Power dissipation capacitance per transceiver.

8.7 Typical Characteristics

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At $T_A = +25^\circ\text{C}$, $V_{CC}=5\text{V}$, unless otherwise noted.

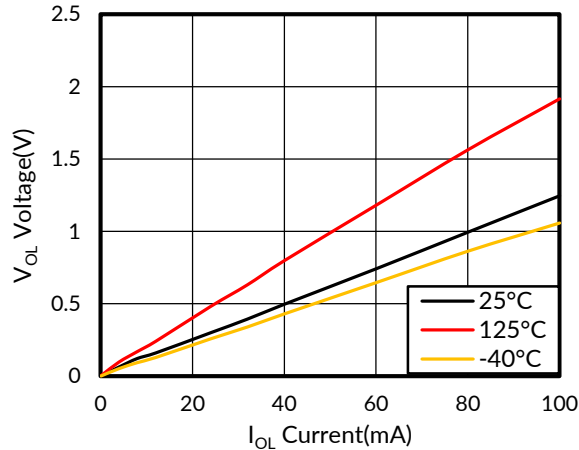


Figure 1. Voltage vs Current

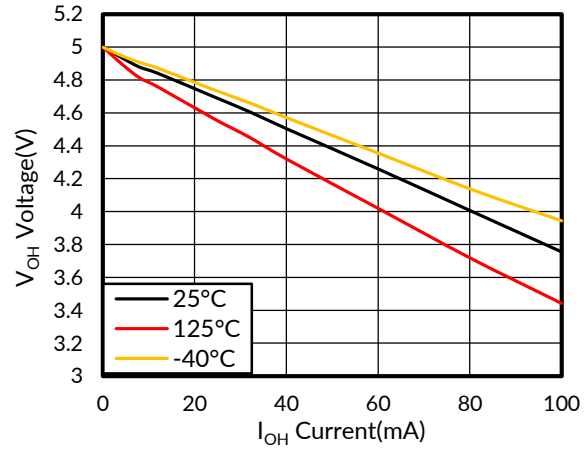
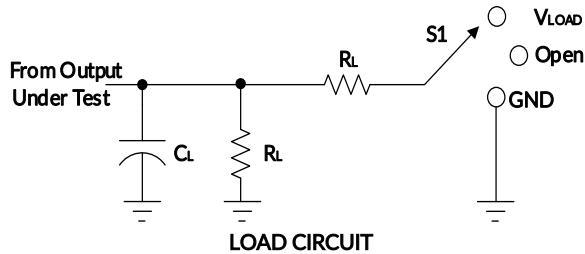


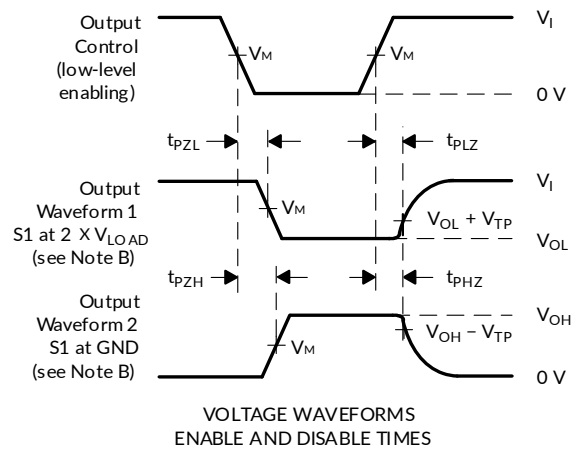
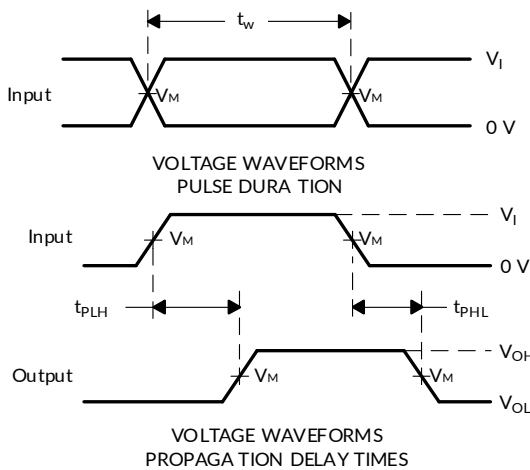
Figure 2. Voltage vs Current

9 Parameter Measurement Information



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

V_{CC}	V_I	V_M	C_L	R_L	V_{TP}
$1.8V \pm 0.15V$	V_{CC}	$V_{CC}/2$	15pF	2k Ω	0.15V
$2.5V \pm 0.2V$	V_{CC}	$V_{CC}/2$	15pF	2k Ω	0.15V
$3.3V \pm 0.3V$	2.7V	1.5V	15pF	2k Ω	0.3V
$5V \pm 0.5V$	2.7V	1.5V	15pF	2k Ω	0.3V



NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50\Omega$, $dv/dt \geq 1V/ns$.

D. The outputs are measured one at a time, with one transition per measurement.

E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

F. t_{PZL} and t_{PZH} are the same as t_{en} .

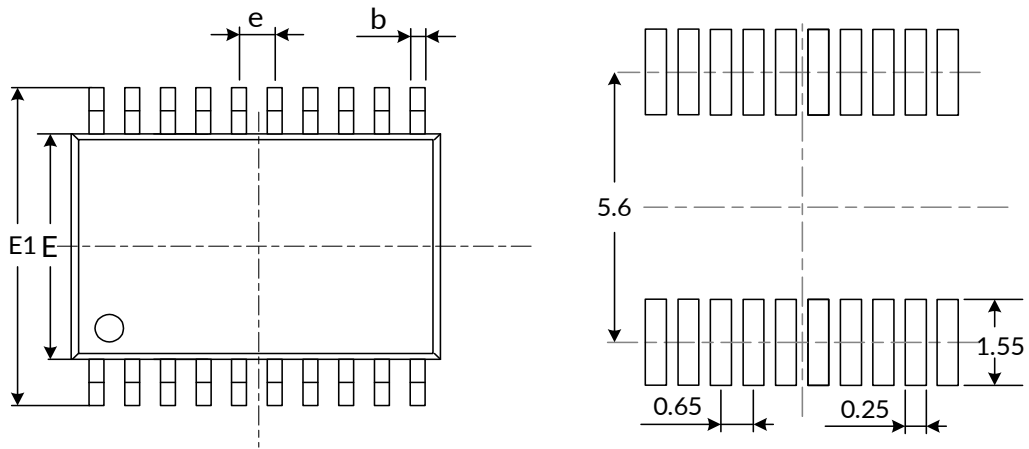
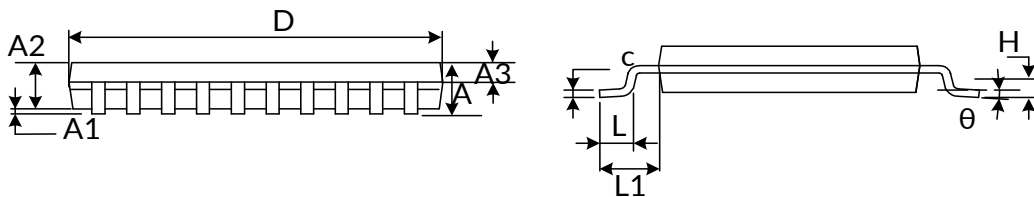
G. t_{PLH} and t_{PHL} are the same as t_{pd} .

H. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

10 PACKAGE OUTLINE DIMENSIONS

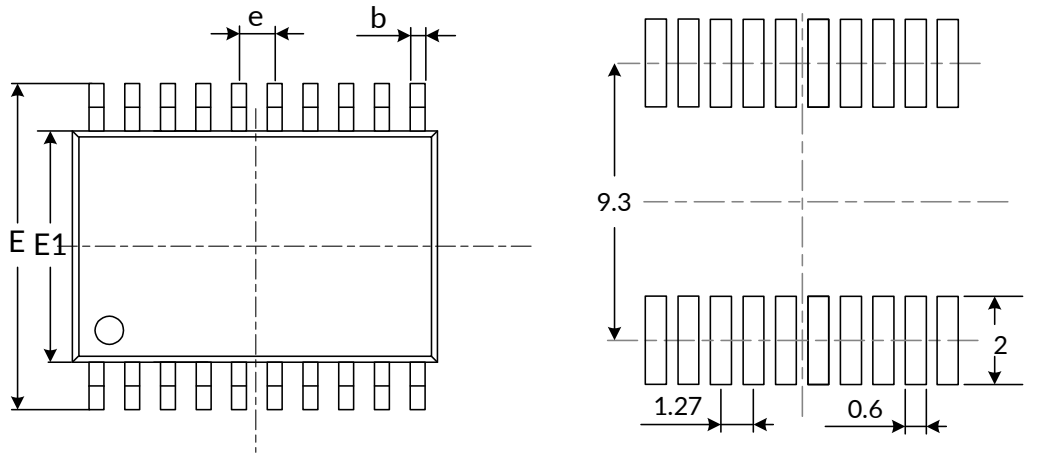
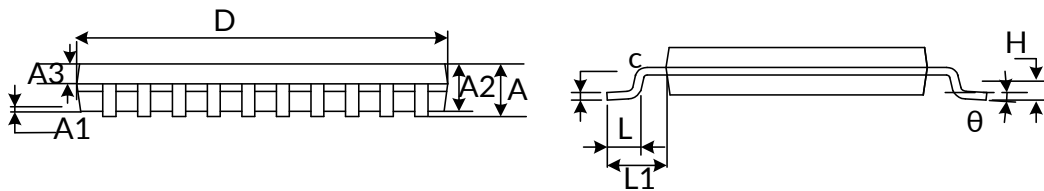
TSSOP20⁽⁴⁾


RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
A3	0.390	0.490	0.015	0.020
b	0.200	0.290	0.008	0.011
c	0.130	0.170	0.005	0.007
D ⁽¹⁾	6.400	6.600	0.252	0.260
E ⁽¹⁾	4.300	4.500	0.169	0.177
E1	6.200	6.600	0.244	0.260
e	0.650(BSC) ⁽²⁾		0.026(BSC) ⁽²⁾	
L	0.450	0.750	0.018	0.030
H	0.250(TYP)		0.010(TYP)	
θ	0°	8°	0°	8°
L1	1.00(REF) ⁽³⁾		0.039(REF) ⁽³⁾	

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. REF is the abbreviation for Reference.
4. This drawing is subject to change without notice.

SOP20⁽⁴⁾

RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾		2.650		0.104
A1	0.100	0.300	0.004	0.012
A2	2.250	2.350	0.089	0.093
A3	0.970	1.070	0.038	0.042
b	0.390	0.470	0.015	0.019
c	0.250	0.290	0.010	0.011
D ⁽¹⁾	12.700	12.900	0.500	0.508
E	10.100	10.500	0.398	0.413
E1 ⁽¹⁾	7.400	7.600	0.291	0.299
e	1.270(BSC) ⁽²⁾		0.050(BSC) ⁽²⁾	
L	0.700	1.000	0.028	0.039
H	0.250(TYP)		0.010(TYP)	
θ	0°	8°	0°	8°
L1	1.400(REF) ⁽³⁾		0.055(REF) ⁽³⁾	

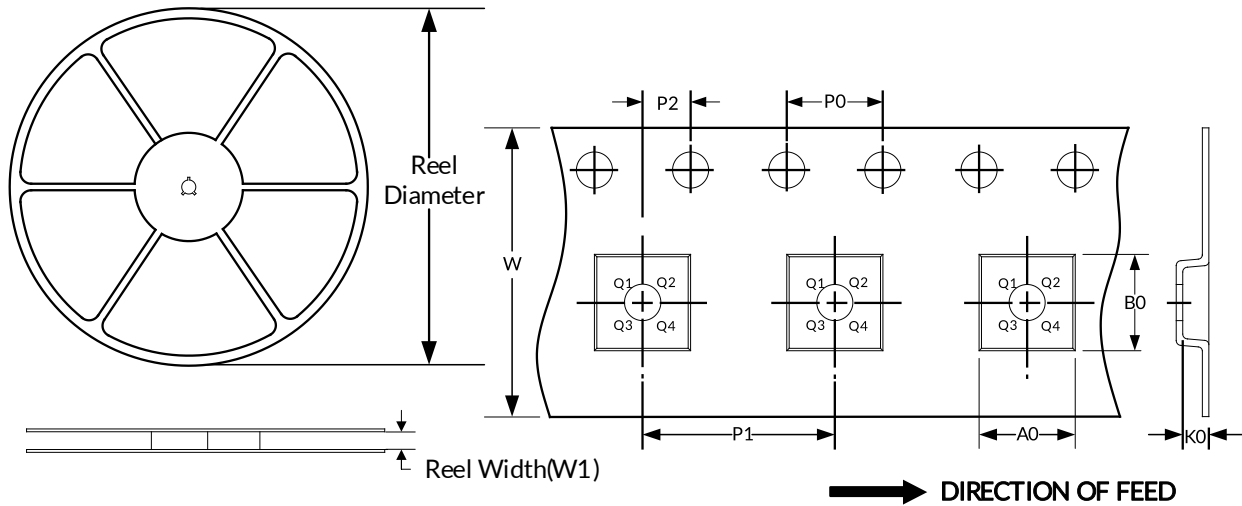
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. REF is the abbreviation for Reference.
4. This drawing is subject to change without notice.

11 TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP20	13"	12.4	6.75	6.95	1.20	4.0	8.0	2.0	12.0	Q1
SOP20	13"	24.4	10.75	13.55	2.65	4.0	12.0	2.0	24.0	Q1

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

IMPORTANT NOTICE AND DISCLAIMER

Jiangsu Runic Technology Co., Ltd. will accurately and reliably provide technical and reliability data (including data sheets), design resources (including reference designs), application or other design advice, WEB tools, safety information and other resources, without warranty of any defect, and will not make any express or implied warranty, including but not limited to the warranty of merchantability Implied warranty that it is suitable for a specific purpose or does not infringe the intellectual property rights of any third party.

These resources are intended for skilled developers designing with Runic products You will be solely responsible for: (1) Selecting the appropriate products for your application; (2) Designing, validating and testing your application; (3) Ensuring your application meets applicable standards and any other safety, security or other requirements; (4) Runic and the Runic logo are registered trademarks of Runic Incorporated. All trademarks are the property of their respective owners; (5) For change details, review the revision history included in any revised document. The resources are subject to change without notice. Our company will not be liable for the use of this product and the infringement of patents or third-party intellectual property rights due to its use.